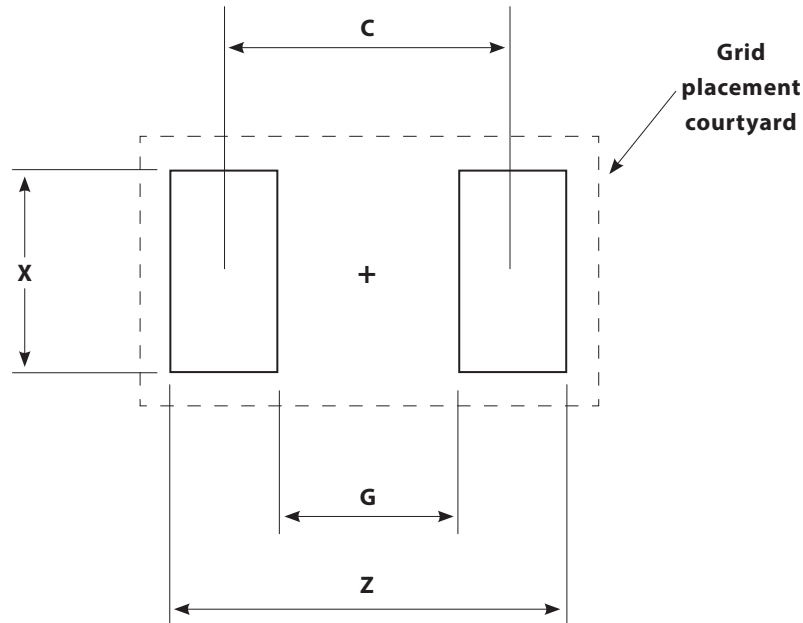


Overview

The figure below provides the land pattern dimensions for capacitors. These numbers represent industry consensus on the best dimensions based on empirical knowledge of fabricated land patterns. The dotted line in the figure below shows the grid placement courtyard which is the area required to place land patterns and their respective components in adjacent proximity without interference or shorting.

Applies to the following Venkel series:

C, HVC, HQN



Component Identifier inches (mm)	Z (mm)	G (mm)	X (mm)	C (mm)
	min.	min.	min.	ref.
01005 (0402)	0.58	0.18	0.21	0.38
0201 (0603)	0.90	0.30	0.42	0.60
0402 (1005)	2.00	0.40	0.60	1.30
0603 (1608)	2.60	0.60	1.00	1.70
0805 (2012)	3.00	0.60	1.20	1.90
1206 (3216)	4.20	1.20	1.40	2.80
1210 (3225)	4.20	1.20	2.40	2.80
2010 (5025)	6.00	2.60	2.40	4.40
2512 (6332)	7.20	3.80	3.00	5.60

Chip capacitor land pattern dimensions

Note: This pattern is a recommendation for pad design. Variations in pad design will depend on individual processing parameters and required circuit design.